

SMD Power Inductor Molded High Current AEC-Q200

SIM06-10MAE series

MERITEK

FEATURE

- High Current, Low DCR, High Efficiency
- Low Acoustic Noise and Shielded Construction Design
- High Resolution in EMC Protection
- Application: Automotive Applications
- AEC-Q200 Grade 0 (-55 ~ +150°C)



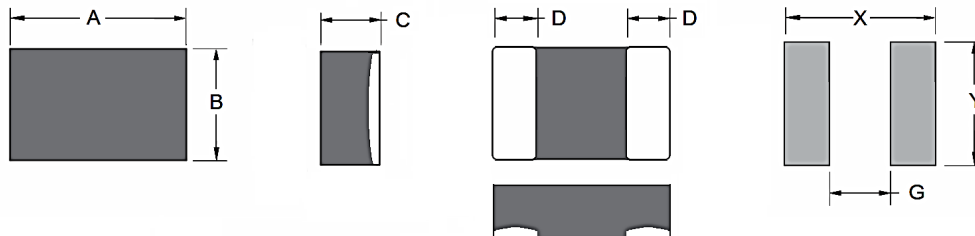
ELECTRICAL CHARACTERISTICS

Part Number	Inductance (μH)	Tolerance (%)	I _{rms} (A)		I _{sat} (A)		DCR (m Ω)	
			Typ	Max	Typ	Max	Typ	Max
SIM06R10M10MAE	0.10	$\pm 20\%$	8.0	7.0	9.0	8.0	7.5	9.0
SIM06R15M10MAE	0.15	$\pm 20\%$	7.5	6.5	8.5	7.5	10.0	12.0
SIM06R22M10MAE	0.22	$\pm 20\%$	7.0	6.0	8.0	7.0	10.5	12.6
SIM06R24M10MAE	0.24	$\pm 20\%$	6.5	5.5	7.7	6.7	18.0	20.5
SIM06R33M10MAE	0.33	$\pm 20\%$	5.7	5.2	7.0	6.2	21.0	26.0
SIM06R47M10MAE	0.47	$\pm 20\%$	5.3	4.7	6.0	5.3	28.0	32.0
SIM06R56M10MAE	0.56	$\pm 20\%$	4.6	4.0	5.2	4.6	31.0	37.2
SIM06R68M10MAE	0.68	$\pm 20\%$	4.0	3.4	5.0	4.4	44.0	50.0
SIM061R0M10MAE	1.00	$\pm 20\%$	3.6	3.2	4.4	3.8	49.0	59.0
SIM061R5M10MAE	1.50	$\pm 20\%$	2.6	2.3	3.0	2.7	80.0	96.0
SIM062R2M10MAE	2.20	$\pm 20\%$	2.3	2.0	2.65	2.45	130.0	150.0
SIM064R7M10MAE	4.70	$\pm 20\%$	1.4	1.2	2.1	1.9	265.0	318.0

Notes:

1. Test frequency: Ls:100KHz/1.0V.
2. Heat Rating Current (I_{rms}) will cause the temperature rise approximately ΔT of 40°C.
3. Saturation Current (I_{sat}) will cause L₀ to drop approximately 30%.
4. Operating Temperature: -55 ~ +150°C (Including self-temperature rise)

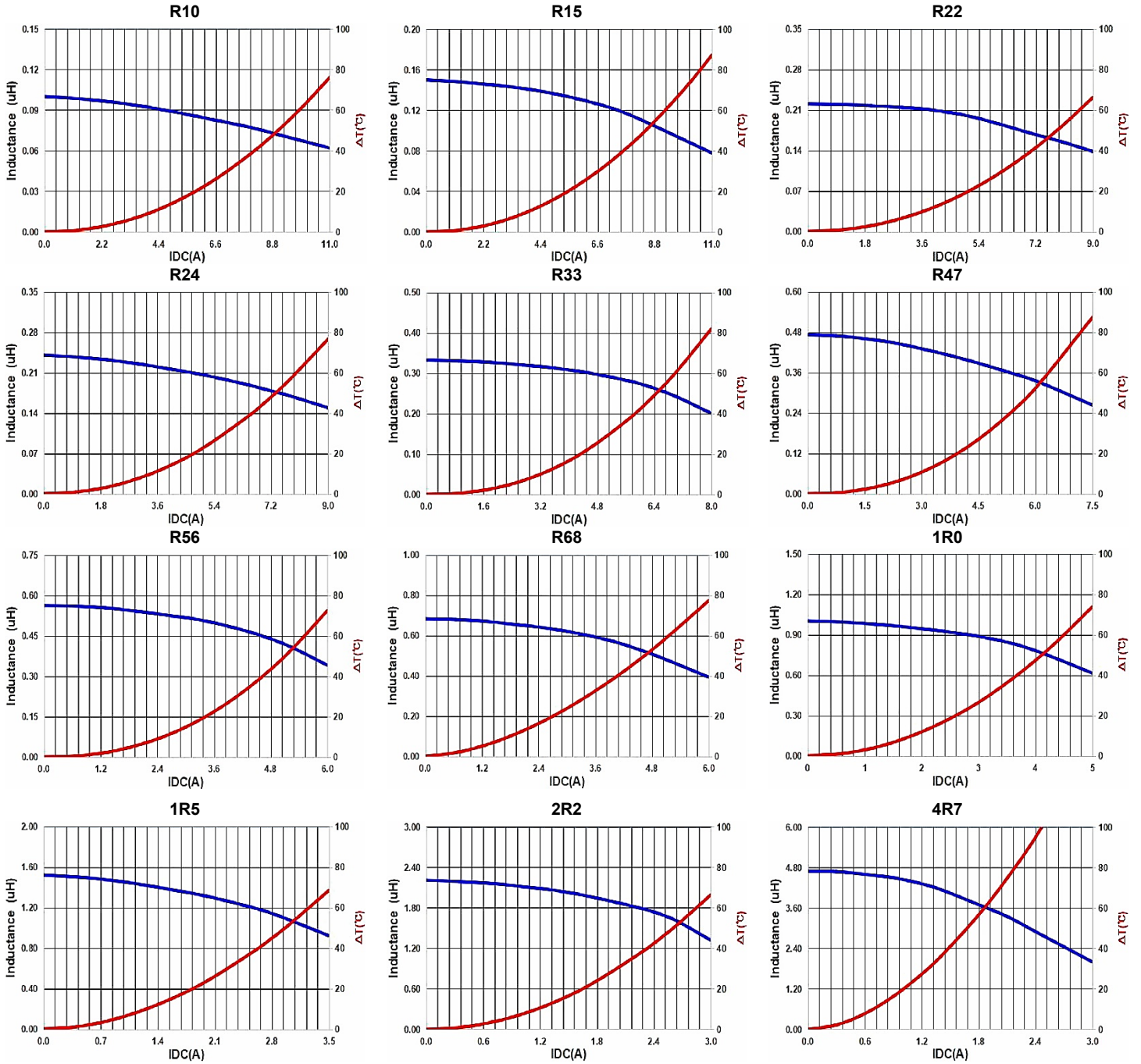
DIMENSIONS



(Unit: mm)

Size Code	A	B	C	D	X	G	Y
0806 (06)	2.0 \pm 0.3	1.6 \pm 0.3	0.8 \pm 0.2	0.7 \pm 0.3	2.5 Ref	0.5 Ref	1.9 Ref

CHARICTERISTIC CURVES – SIM06-10MAE SERIES



SMD Power Inductor Molded High Current AEC-Q200

SIM06-10MAE series

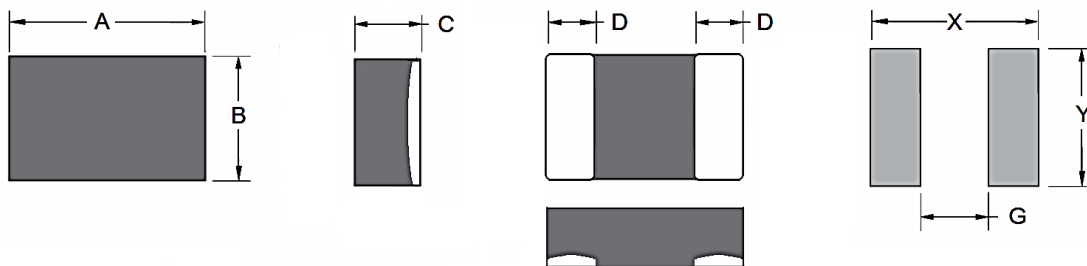
MERITEK

PART NUMBERING SYSTEM

SIM **06** **R24M** **10** **MAE**
(1) (2) (3) (4) (5)

No	item	Code	Description	
(1)	Product Code	SIM	SMD Power Inductor Series, High current Molded type	
(2)	Size Code	06	0806: 2.0x1.6mm (W x L)	
(3)	Nominal Inductance	R24M	0.24 μ H \pm 20% (M)	R denotes decimal point
(4)	Thickness Code	10	10: 0.8 \pm 0.2mm	12: 1.0 \pm 0.2mm, 20: 1.8 \pm 0.2mm
(5)	Series Code	MAE	High current molded series, AEC-200 Compliant	

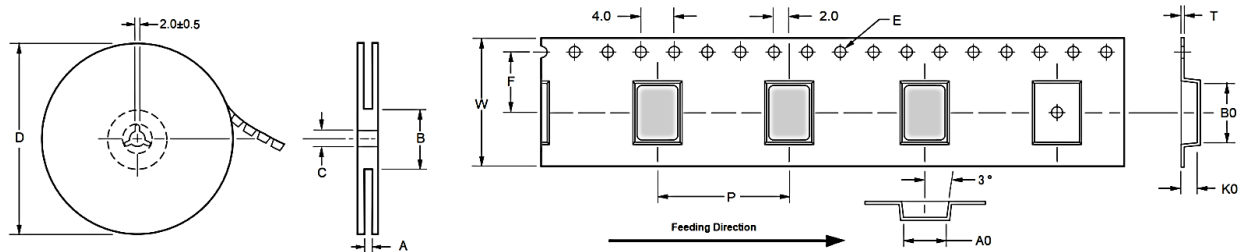
DIMENSIONS – SIM-MAE SERIES



(Unit: mm)

Series	Size	A	B	C	D	X	G	Y
SIM06-10MAE	0806	2.0 \pm 0.3	1.6 \pm 0.3	0.8 \pm 0.2	0.7 \pm 0.3	2.5 Ref	0.5 Ref	1.9 Ref
SIM08-10MAE	1008	2.5 \pm 0.3	2.0 \pm 0.3	0.8 \pm 0.2	0.9 \pm 0.3	2.9 Ref	0.5 Ref	2.3 Ref
SIM08-12MAE	1008	2.5 \pm 0.3	2.0 \pm 0.3	1.0 \pm 0.2	0.9 \pm 0.3	2.9 Ref	0.5 Ref	2.3 Ref
SIM10-12MAE	1210	3.2 \pm 0.3	2.5 \pm 0.3	1.0 \pm 0.2	1.1 \pm 0.3	3.7 Ref	0.7 Ref	2.8 Ref
SIM10-20MAE	1210	3.2 \pm 0.3	2.5 \pm 0.3	1.8 \pm 0.2	1.1 \pm 0.3	3.7 Ref	0.7 Ref	2.8 Ref

PACKAGING DIMENSION



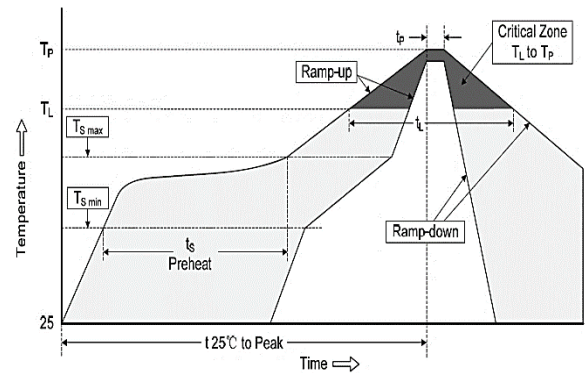
(Unit: mm)

Size Code	Reel Dimension				Tape Dimensions								Qty
	A \pm 1.0	B \pm 0.5	C \pm 0.5	D	W \pm 0.1	F \pm 0.01	P \pm 0.1	E \pm 0.1	A0 \pm 0.10	B0 \pm 0.1	K0 \pm 0.10	T \pm 0.05	7" Reel
0806	8.4	50	13.0	178.0	8.00	3.5	4.0	1.50	2.00	2.50	1.20	0.23	2000
1008	8.4	50	13.0	178.0	8.00	3.5	4.0	1.50	2.45	2.90	1.35	0.24	2000
1008	8.4	50	13.0	178.0	8.00	3.5	4.0	1.50	2.45	2.90	1.35	0.24	2000
1210	8.4	50	13.0	178.0	8.00	3.5	4.0	1.50	2.90	3.60	1.40	0.22	2000
1210	8.4	50	13.0	178.0	8.00	3.5	4.0	1.50	2.90	3.60	2.20	0.22	2000

RECOMMENDED SOLDERING PROFILES

Reflow Condition		
Pre Heat	Temperature Min $T_{s(min)}$	150°C
	Temperature Max $T_{s(max)}$	200°C
	Time (min. to max.) (t_s)	60 ~120 seconds
Ramp up rate (T_L to T_P)		3°C/second max
$T_{s(max)}$ to T_L (Ramp-up rate)		3°C/second max
Reflow	Temperature (T_L)	217°C
	Time (min. to max.) (t_L)	60 ~150 seconds
Peak Temperature (T_P)		See table below
t_p within 5°C of Peak Temperature (T_P)		30 seconds max
Ramp-down Rate		6°C/second max
Time 25°C to Peak Temperature		8 minutes max

Peak Temperature (T_P)			
Volume	< 350mm ³	350-2000mm ³	> 2000mm ³
Thickness < 1.6mm	260°C	260°C	260°C
Thickness 1.6-2.5mm	260°C	250°C	245°C
Thickness ≥ 2.5mm	250°C	245°C	245°C



*Specifications subject to change without notice.